WLCSP51, 2.364x2.325
CASE 567MT
ISSUE A

DATE 13 DEC 2016

SCALE 4:1

PIN A1 REFERENCE

E A B

D

2X ⌒ 0.05 C

2X ⌒ 0.05 C

TOP VIEW

⟋ 0.08 C

A3

A A2

A1

⌒ 0.03 C

NOTE 3

SIDE VIEW

C SEATING PLANE

F

e/2

e

51X ⌀ b

⊕ 0.05 C A B
0.03 C

L K J H G F E D C B A

1 2 3 4 5 6 7 8 9 10 11

e
e/2

BOTTOM VIEW
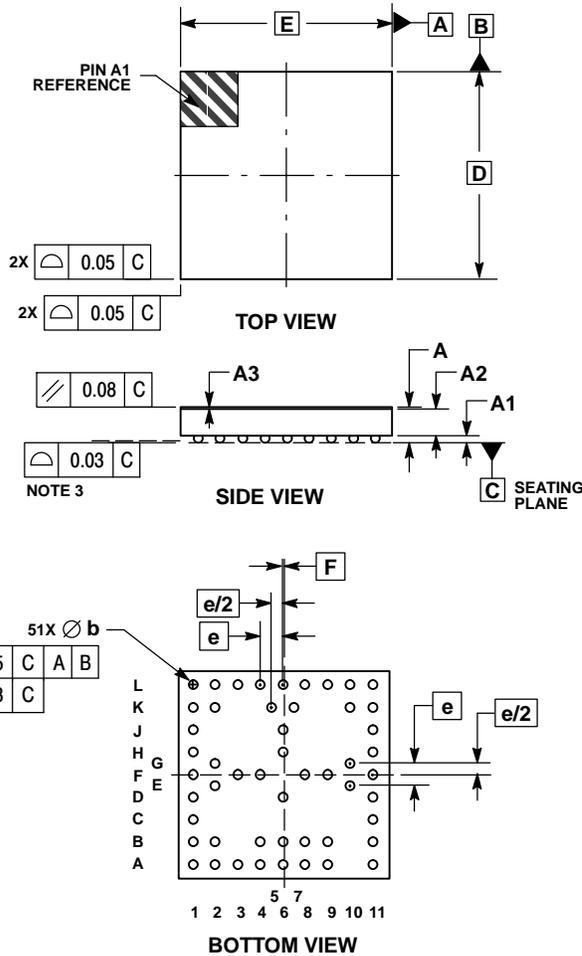
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.
4. PACKAGE CENTER AND FOOTPRINT CENTER ARE NOT COINCIDENT. REFER TO DIMENSION F FOR OFFSETS.

| DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.319	0.350	0.381
A1	0.060	0.075	0.090
A2	0.237	0.250	0.263
A3	0.022	0.025	0.028
b	0.09	0.10	0.12
D	2.325 BSC		
E	2.364 BSC		
e	0.252 BSC		
F	0.0198 BSC		

GENERIC MARKING DIAGRAM*

XXXXXXX
XXXXXXX
AWLYYWW
▪

XXXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
▪ = Pb–Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*

0.0198

0.252 PITCH

A1

0.252 PITCH

0.126
NOTE 4

51X
⌀ 0.10

DIMENSIONS: MILLIMETERS
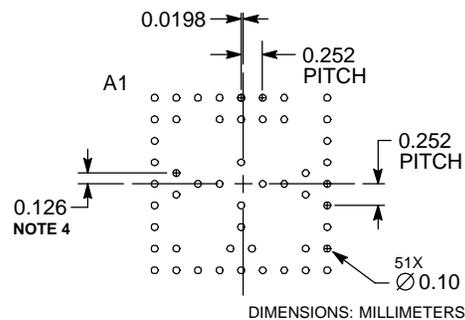
*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON05534G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
STATUS:	ON SEMICONDUCTOR STANDARD		
NEW STANDARD:			
DESCRIPTION:	WLCSP51, 2.364X2.325		PAGE 1 OF 2

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY B. BLAUER.	20 NOV 2015
A	MODIFIED DIMENSIONS A, A1, B, D, E AND F. ADDED DIMENSIONS A2 AND A3. REMOVED DIMENSION G. REQ. BY C. ENRIQUEZ.	13 DEC 2016